

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet



SMA

FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Super fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals

MECHANICAL DATA

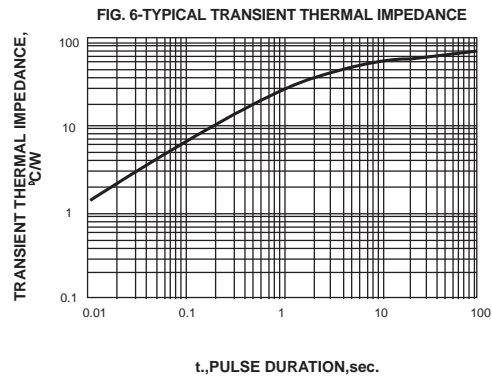
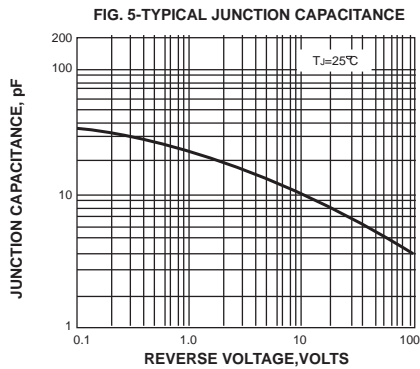
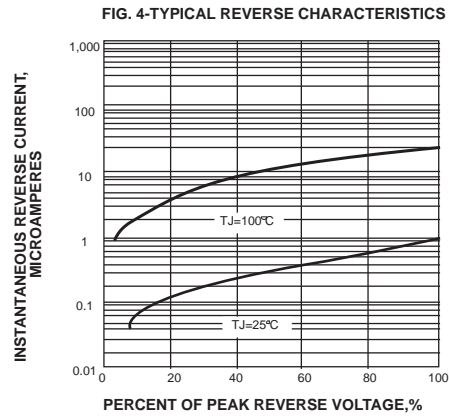
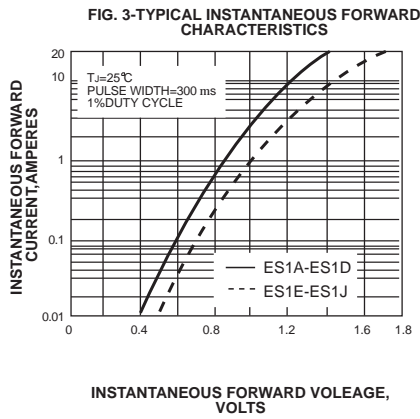
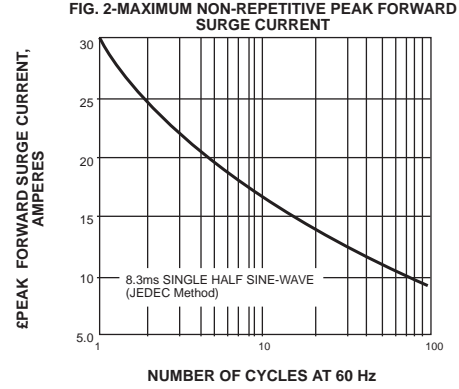
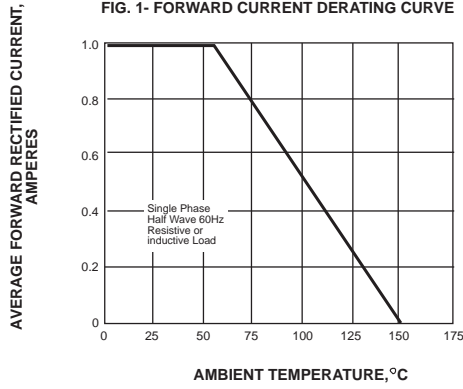
- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any
- ◆ **Weight:** 0.003 ounce, 0.093 grams
0.004 ounce, 0.111 grams SMA(H)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

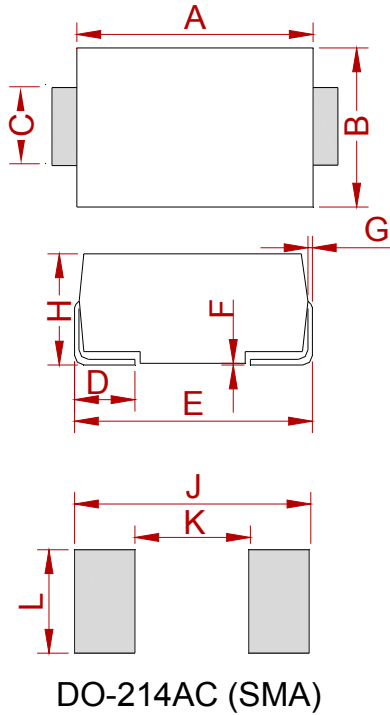
Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	ES1A	ES1B	ES1C	ES1D	ES1E	ES1G	ES1J	UNITS	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	VOLTS	
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	VOLTS	
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	VOLTS	
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	1.0							Amp	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30.0							Amps	
Maximum instantaneous forward voltage at 1.0A	V_F	0.95				1.25			Volts	
Maximum DC reverse current at rated DC blocking voltage	I_R	5.0				50.0				uA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35								ns
Typical junction capacitance (NOTE 2)	C_J	15.0								pF
Typical thermal resistance (NOTE 3)	R_{qJA}	60.0								°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-65 to +150							°C	

Note: 1. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
ES1A THRU ES1J	SMA	2000

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